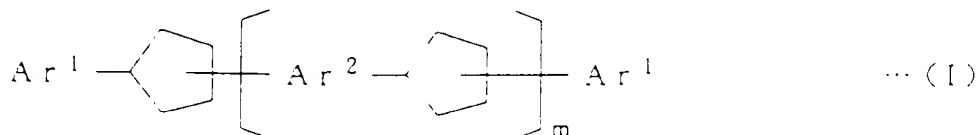


ABSTRACT

This invention provides, ~~as a novel compound~~ ^{suitable} ~~as an encapsulating material for electronic devices,~~ ^{and} having
 a high Tg, ~~being~~ ^{on} low moisture-absorptive, ~~having a high~~
 adhesion and ~~being rich in~~ ^{fluidity} a cyclopentylene
 compound represented by Formula (I) and its intermediate
 cyclopentenyl compound represented by Formula (III). In
 the formula, m is 0 or more, Ar¹ and Ar² are each a phenol
 residual group, a naphthol residual group or a fluorene
 derivative residual group, and each contain a hydroxyl
 group or a glycidyloxy group.



~~This invention also provides a resin composition and~~
~~a molding material which contain the cyclopentylene~~
~~compound of Formula (I), and an electronic device~~
~~encapsulated with the molding material.~~